



Material Content Data Sheet



Sales Product Name		BSC090N03LS G		Issued		1. August 2018		
MA#		MA001343734						
Package		PG-TDSON-8-5		Weight*		123.54 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.743	0.60	0.60	6018	6018
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		92	
	non noble metal	iron	7439-89-6	0.038	0.03		306	
	non noble metal	copper	7440-50-8	37.762	30.57	30.61	305668	306066
	non noble metal	copper	7440-50-8	0.059	0.05	0.05	477	477
wire	non noble metal	copper	7440-50-8	0.059	0.05	0.05	477	477
encapsulation	organic material	carbon black	1333-86-4	0.097	0.08		787	
	plastics	epoxy resin	-	6.899	5.58		55845	
	inorganic material	silicondioxide	60676-86-0	41.588	33.66	39.32	336645	393277
leadfinish	non noble metal	tin	7440-31-5	1.452	1.18	1.18	11751	11751
plating	noble metal	silver	7440-22-4	0.166	0.13	0.13	1340	1340
solder	non noble metal	tin	7440-31-5	0.021	0.02		173	
	noble metal	silver	7440-22-4	0.027	0.02		216	
	non noble metal	lead	7439-92-1	1.019	0.83	0.87	8252	8641
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	iron	7439-89-6	0.011	0.01		92	
	non noble metal	copper	7440-50-8	11.320	9.16	9.17	91632	91752
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		54	
	non noble metal	iron	7439-89-6	0.022	0.02		181	
	non noble metal	copper	7440-50-8	22.292	18.04	18.07	180443	180678
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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